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CITY (TW)(57) **ABSTRACT**

A heat dissipation device includes a case, a first board, a second board, a curved supporting structure, and a fan. The first board is disposed in the case. The curved supporting structure has a curved slot which is located on an inner surface of the curved supporting structure, and the curved slot extends radially with respect to a center of the curved supporting structure. The second board is inserted in the curved slot, and the first board, the second board, and the curved supporting structure collectively form an accommodating space. The fan is fixed to the second board and disposed within the accommodating space.

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